

- **Bill of Materials**
 - Assembly name and revision
 - PCB part number and PCB revision
 - Reference designators with corresponding quantities
 - Part numbers (those used in your system)
 - Manufacturers and manufacturer part numbers
 - Component descriptions
 - If firmware is required, please list each firmware as a BoM line item (include revision)
 - Indicate approved alternate components
- **CAD (ASCII data)**
 - This data is needed to perform a design for manufacturing (DFM) analysis
 - Acceptable formats include: .pcb, .min, .asc or ODB++
- **PCB Gerber files**
 - Please include outside board dimensions and PCB fab specs
 - RS-274X extended Gerber format preferred, Rs-274D acceptable
- **Requirements**
 - IPC Class 2 or Class 3?
 - Solder type: Leaded or Lead-free?
 - Flux type preference: Water soluble or no-clean?
 - Compliance: RoHS or Non-RoHS?
 - Special instructions/processes:
 - Pre-bake
 - Conformal coat
 - Lot traceability
 - Potting
 - Other
- **Testing (if applicable)**
 - Test/burn-in requirements (include procedures)
 - Describe test equipment required
 - Schematic(s) (PDF preferred)
- **Box Build (if applicable)**
 - Mechanical assembly drawings and specifications (PDF preferred, Solid Works acceptable)
- **Not Required, But Preferred:**
 - Assembly drawings for SMT component locations/orientation